MP8840

8-Channel, Voltage Output, 2 MHz, 4 Quadrant Multiplying, 8-Bit DAC with Serial Digital Data Port

September 1998-2

FEATURES

- 8 Independent 4-Quadrant Multiplying 8-Bit DACs
- High Speed:
  - Settling Time: 3.5 μs to ±1 LSB
  - Slew Rate: 4 V/μs
  - Voltage Reference Input Bandwidth: 2.5 MHz (V_{IN} = 100 mV p-p)
- Low Power: 80 mW (typ)
- DACs Matched to ±0.5% (typ)
- Midscale Preset, All DAC Outputs are Zero Volts
- Latch-Up Free
- Greater than 2000 V ESD Protection
- 5 MHz Version: MP7670
- Guaranteed Monotonic

APPLICATIONS

- Analog Multiplier Replacement
- High-Frequency Gain Control using DACs
- Convergence Adjustment for Displays and Monitors
- Potentiometer Adjustment Replacement

GENERAL DESCRIPTION

The MP8840 is an 8-channel, 4 quadrant multiplying, 8-bit accurate digital-to-analog converter with a 2.5 MHz input bandwidth. It includes an output drive amplifier per channel capable of driving a ±5 mA minimum to a load. DNL of ±1/4 LSB (typ) is achieved with a channel-to-channel matching of better than 0.5% (typ). Stability, matching, and precision of the DACs are achieved by using EXAR's thin film technology.

The MP8840 is ideal for direct gain control of high frequency analog signals. The bipolar output amplifier has low noise which produces a very sharp signal output particularly in display and monitor applications.

A proprietary subranging architecture provides wide signal bandwidth from V_{IN} to output up to 2.5 MHz (typ), fast output settling time, and V_{IN} feedthrough isolation of -60dB (typ).

The MP8840 has a serial data 3-wire standard μ-processor logic interface to reduce pin count, package size, and board wire (space).

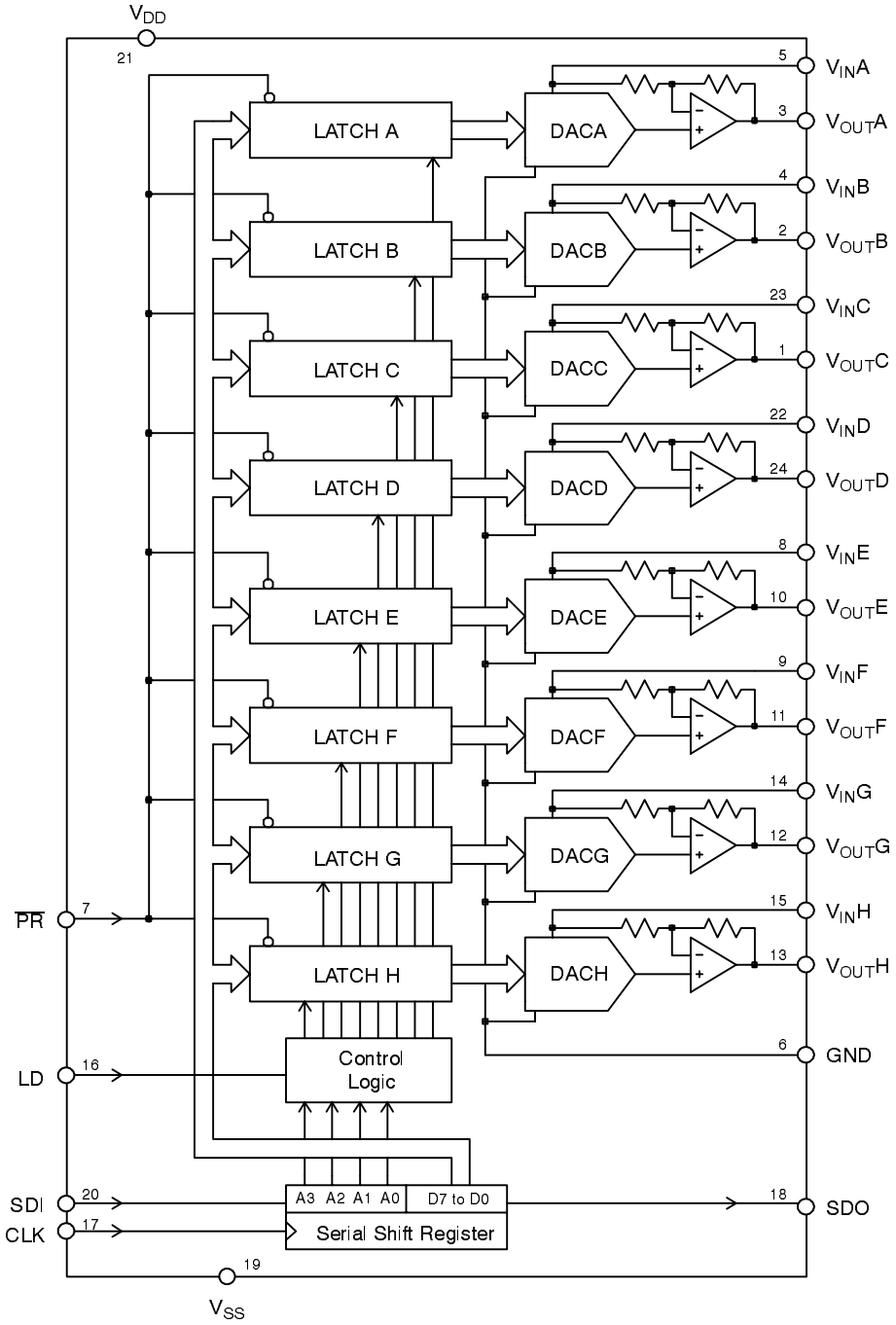
The MP8840 is fabricated on a junction isolated, high speed BiCMOS1™ process with thin film resistors.

ORDERING INFORMATION

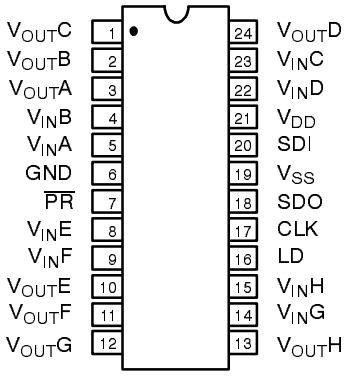
Package Type	Temperature Range	Part No.
Plastic Dip	-40 to +85°C	MP8840AN
SOIC	-40 to +85°C	MP8840AS

EXAR Corporation, 48720 Kato Road, Fremont, CA 94538 ◆ (510) 668-7000 ◆ (510) 668-7017

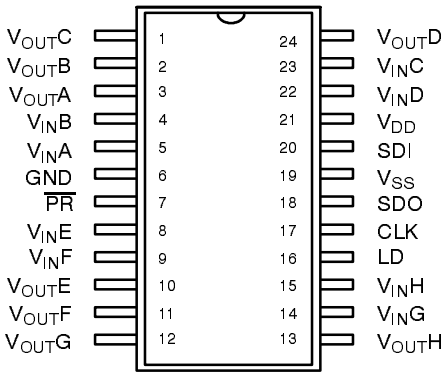
SIMPLIFIED BLOCK DIAGRAM



PIN CONFIGURATIONS



24 Pin PDIP (0.300")



24 Pin SOIC (Jedec, 0.300")

PIN DESCRIPTION

PIN NO.	NAME	DESCRIPTION
1	$V_{OUT}C$	DAC C Output
2	$V_{OUT}B$	DAC B Output
3	$V_{OUT}A$	DAC A Output
4	$V_{IN}B$	DAC B Reference Input
5	$V_{IN}A$	DAC A Reference Input
6	GND	Ground
7	$\overline{PR}$	Preset Input, Active Low
8	$V_{IN}E$	DAC E Reference Input
9	$V_{IN}F$	DAC F Reference Input
10	$V_{OUT}E$	DAC E Output
11	$V_{OUT}F$	DAC F Output
12	$V_{OUT}G$	DAC G Output

PIN NO.	NAME	DESCRIPTION
13	$V_{OUT}H$	DAC H Output
14	$V_{IN}G$	DAC G Reference Input
15	$V_{IN}H$	DAC H Reference Input
16	LD	Load DAC Register Strobe, Active High Input
17	CLK	Serial Clock Input
18	SDO	Serial Data Output
19	V_{SS}	Negative Power Supply
20	SDI	Serial Data Input
21	V_{DD}	Positive Power Supply
22	$V_{IN}D$	DAC D Reference Input
23	$V_{IN}C$	DAC C Reference Input
24	$V_{OUT}D$	DAC D Output

ELECTRICAL CHARACTERISTICS TABLE FOR DUAL SUPPLIES

Unless Otherwise Noted: V_{DD} = 5 V, V_{SS} = -5 V, GND = 0 V, $V_{IN}X$ =3 V

Parameter	Symbol	25°C Min	25°C Typ	25°C Max	Tmin to Tmax Min	Tmin to Tmax Max	Units	Test Conditions/Comments
DC CHARACTERISTICS								
Resolution (All Grades)	N	8			8		Bits	
Differential Non-Linearity	DNL		±1/4	±1		±1	LSB	
Integral Non-Linearity	INL			±1		±1	LSB	
Monotonicity			Guaranteed					
DAC OUTPUT								
Output Offset	V_{BZE}		3	25			mV	$\overline{PR}$ = 0, Sets Code = 80_H
Voltage Range	OVR	-3		3	-3	3	V	
Output Current	I_{OUT}	±5	±10		±5		mA	ΔV_{OUT} <1 LSB
Capacitive Load	CL			200		200	pF	No oscillations
REFERENCE INPUTS								
Input Resistance of one DAC	R_{IN}	5			5		KΩ	R_{IN} (typ) = 15KΩ//Rx Rx = 20KΩ/(1-Code/256)
Input Capacitance[2]	C_{IN}		19	30			pF	
Voltage Range[1]	IVR	-3		3	-3	3	V	
DYNAMIC CHARACTERISTICS[2]								
Input to Output Bandwidth	BW	1	2.5				MHz	Code = FS, $V_{IN}X$ = 100 mV p-p
Slew Rate	SR	1.3	4.0				V/µs	Measured 10% to 90%, $\Delta V_{OUT}X$ = ±6 V
V_{IN} Feedthrough	F_{DT}		-60				dB	Code = HS, up to f = 100 kHz
Total Harmonic Distortion	T_{HD}		0.02				%	$V_{IN}X$ = 4 V p-p, Code = FS f = 1 kHz, f_{LP} = 80 kHz
Spot Noise Voltage	e_N		0.17				µV/√Hz	f = 1 kHz
Output Settling Time	t_S		3.5	6.0			µs	±1 LSB, Code = 0 to FS
Channel-to-Channel Crosstalk	C_T	60					dB	Measured between adjacent channels, f = 100 kHz
Digital Feedthrough	Q		6				nVs	$V_{IN}X$ = 0 V, Code = 0 to FS
DIGITAL INPUTS								
Logic High[3]	V_{IH}	2.4			2.4		V	
Logic Low[3]	V_{IL}			0.8		0.8	V	
Input Current	I_L			±1		±1	µA	
Input Capacitance[2]	C_L			8		8	pF	
DIGITAL OUTPUTS								
Logic High	V_{OH}	3.5			3.5			I_{OH} = -0.4 mA
Logic Low	V_{OL}			0.4		0.4		I_{OL} = 1.6 mA
POWER SUPPLIES								
Power Supply Range	V_{DD}	4.5		5.5	4.5	5.5	V	
	V_{SS}	-5.5		-4.5	-5.5	-4.5	V	
Power Supply Rejection Ratio								
Positive	PSRR+		0.0002	0.01			%/%	$\overline{PR}$ = 0 V, ΔV_{DD} = ±5%
Negative	PSRR-		0.0002	0.01			%/%	$\overline{PR}$ = 0 V, ΔV_{SS} = ±5%

ELECTRICAL CHARACTERISTICS TABLE

Description	Symbol	25°C Min	25°C Typ	25°C Max	Tmin to Tmax Min	Tmin to Tmax Max	Units	Conditions
POWER SUPPLIES (CONT'D)								
Power Dissipation	P_{DISS}		80	150			mW	$\overline{PR}$ = 0 V
Power Supply Current	I_{DD}		8	15			mA	$\overline{PR}$ = 0 V
Negative Supply Current	I_{SS}		8	15			mA	$\overline{PR}$ = 0 V
DIGITAL TIMING SPECIFICATIONS[2, 4]								
Input Clock Pulse Width	t_{CH}, t_{CL}	80					ns	
Data Setup Time	t_{DS}	40					ns	
Data Hold Time	t_{DH}	20					ns	
CLK to SDO Propagation Delay	t_{PD}			160			ns	
Load Pulse Width	t_{LD}	70					ns	
Preset Pulse Width	t_{PR}	50					ns	
Clock Edge to Load	t_{CKLD}	30					ns	
Load Edge to Next Clk Edge	t_{LDCK}	60					ns	

Notes:

1 *Maximum input voltage is 2 V less than V_{DD}.*

2 *Guaranteed but not production tested.*

3 *Digital input levels should not go below ground or exceed the positive supply voltage, otherwise damage may occur.*

4 *See timing diagram.*

Specifications are subject to change without notice

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C unless otherwise noted)[1, 2]

V_{DD} to GND ..... +6.5 V
V_{SS} to GND ..... -6.5 V
V_{INA-H} to GND ..... V_{DD} to V_{SS}
V_{OUTA-H} to GND ..... V_{DD} to V_{SS}
Digital Input & Output Voltage to GND .. -0.5 to V_{DD} +0.5 V
Operating Temperature Range
Extended Industrial ..... -40°C to +85°C

Maximum Junction Temperature ..... -65°C to +150°C
Storage Temperature ..... 150°C
Lead Temperature (Soldering 10 seconds) ..... +300°C
Package Power Dissipation Rating @ 75°C
PDIP, SOIC 1000mW
Derates above 75°C ..... 14mW/°C

NOTES:

1 *Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.*

2 *Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies. All inputs have protection diodes which will protect the device from short transients outside the supplies of less than 100mA for less than 100µs.*

THEORY OF OPERATION

The MP8840 contains 8 independent 4-quadrant multiplying D/A converters with output amplifiers. The design has incorporated a novel approach that provides fast, accurate, low noise, low distortion, small size, and low power in the same device. This device is particularly useful in applications where multipliers are used to perform the gain adjustment function for high frequency analog signal conditioning. Also note that typical multipliers tend to increase noise particularly for low gain settings and have high offsets. The MP8840 design delivers a very low, constant noise, and low offset with digital control through the entire gain range of the D/A converter.

Linearity Characteristics

Each D/A converter in the MP8840 achieves DNL $\leq \pm 0.25$ LSB (typ), and gain error $\leq \pm 0.5\%$ (typ). Since all 8 channels of MP8840 are fabricated in the same IC, the linearity, gain, and input-output characteristics of all 8 channels match extremely well.

The Logic Interface and Serial Port

The MP8840 is equipped with a serial data 3-wire standard μ-processor logic interface to reduce pin count, package size, and board wire. This interface consists of LD which controls the transfer of data to the selected DAC channels that are fed through the SDI (serial digital data and address bits) with the CLK (digital input shift register clock). Please refer to the following timing diagrams and truth tables for logic details.

A SDO (serial digital data output driver) is connected to the other side of the input shift register and would save SDI bus space by allowing the daisy chaining of several MP8840s (connecting SDI of device 2 to SDO of device 1).

When the LD signal is low, CLK signal loads the digital input bits (SDI) into the 12-bit shift register. The LD signal going high loads this data into the selected DACs. Also, when the $\overline{PR}$ signal is low, the output of all DACs would be reset to 0 volts.

Power Supplies and Input Voltage Ranges

The output and input DC ranges are limited to within ± 2 V from each positive and negative supplies. For example, with supplies at ± 5V, the recommended output range is ± 3V.

The MP8840 design eliminates any code dependent current change into its GND, hence easing the board level design by eliminating the stringent need for other types of DACs for low GND impedance wiring considerations at board level.

Each output of the MP8840 DAC has an output amplifier driver delivering less than 0.05Ω of output impedance through a push-pull linear output stage. Each output and input characteristics parameter match extremely well, given that all channels are fabricated in the same IC.

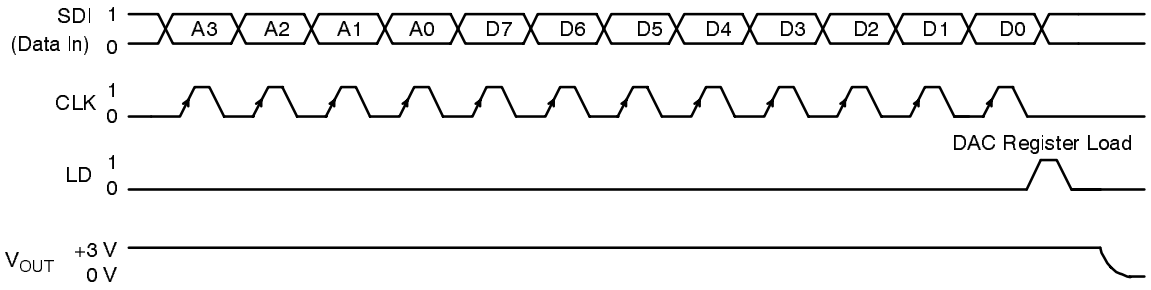


Figure 1. Serial Data Timing and Loading

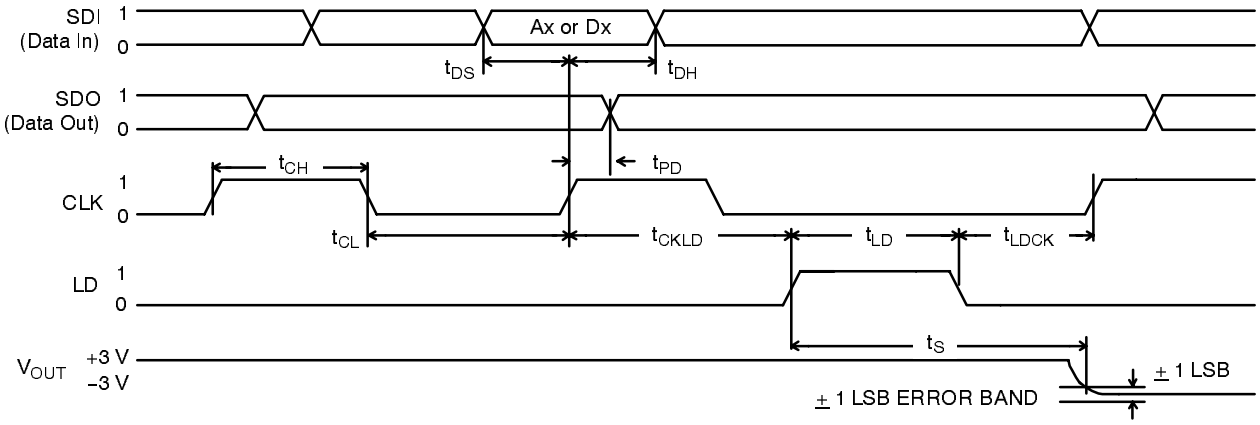


Figure 2. Detail Serial Data Input Timing ($\overline{PR}$ = "1")

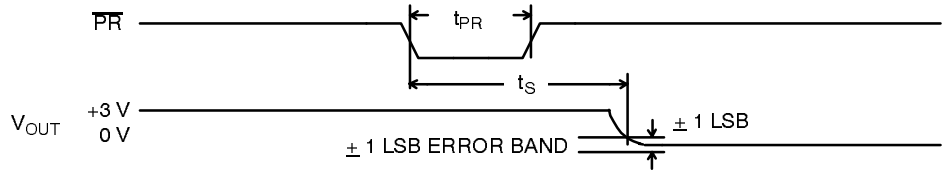
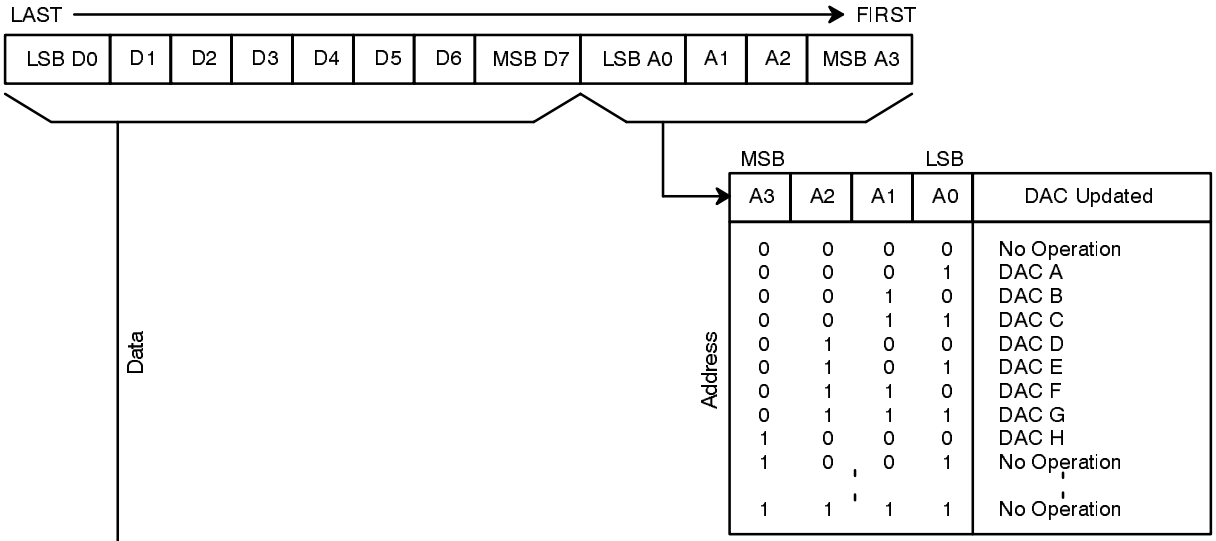


Figure 3. PRESET Operation



MSB LSB

D7	D6	D5	D4	D3	D2	D1	D0	DAC Output Voltage $V_{OUT} = (D/128 - 1) \times V_{IN}$
0	0	0	0	0	0	0	0	$-V_{IN}$
0	0	0	0	0	0	0	1	$(1/128-1) \times V_{IN}$
0	1	1	1	1	1	1	1	$(127/128-1) \times V_{IN}$
1	0	0	0	0	0	0	0	$(128/128-1) \times V_{IN} = 0$ V, (Preset Value)
1	0	0	0	0	0	0	1	$(129/128-1) \times V_{IN}$
1	1	1	1	1	1	1	0	$(254/128-1) \times V_{IN}$
1	1	1	1	1	1	1	1	$(255/128-1) \times V_{IN} \approx V_{IN}$

Table 1. Serial Input Format

SDI	CLK	LD	$\overline{PR}$	Input Shift Register Operation
X	L	L	H	No Operation
X	↑	L	H	Shift One Bit In from SDI (Pin 20), Shift One Bit* Out from SDO (Pin 18)
X	X	L	L	All DAC Registers = 80_H
X	L	H	H	Load Serial Register Data into DAC(X) Register

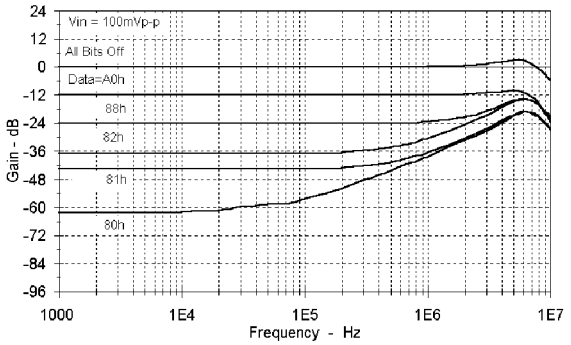
*Data shifted into the SDI pin appears twelve clocks later at the SDO pin.

Table 2. Control Logic Truth Table

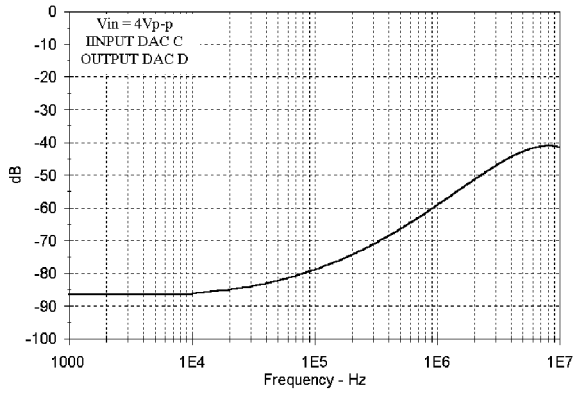
Decimal Input (D)	V_{OUT} (D)	Comments (V_{IN} = 3 V)
0	-3.00 V	Inverted FS
1	-2.98	
127	-0.02	
128	0.00	Zero Output
129	0.02	
254	2.95	
255	2.98	Full Scale (FS)

Table 3. DAC Transfer Function

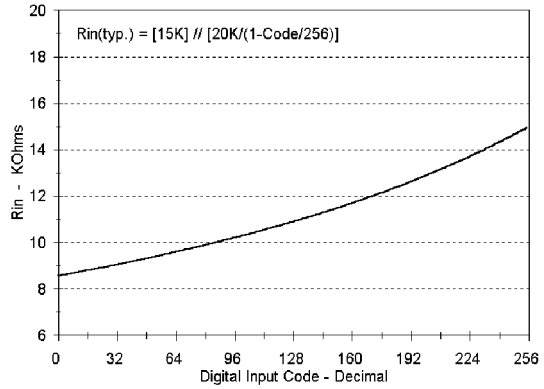
PERFORMANCE CHARACTERISTICS



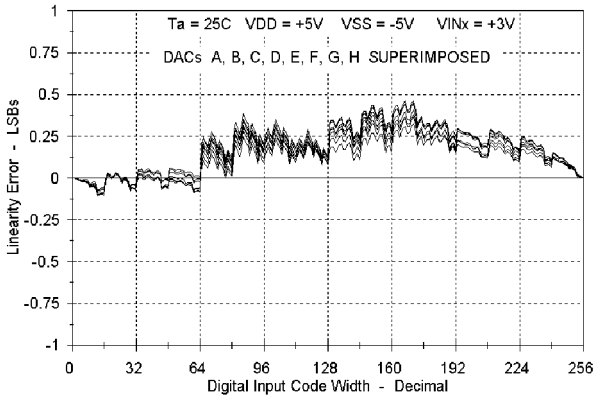
Graph 1. Gain (V_{OUT}/V_{IN}) and Feedthrough vs. Frequency



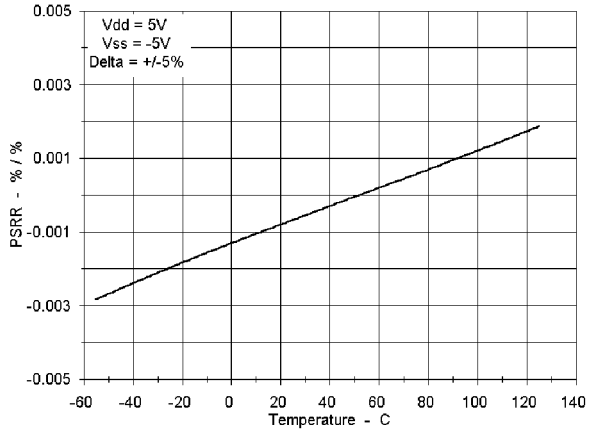
Graph 2. DAC Crosstalk vs. Frequency



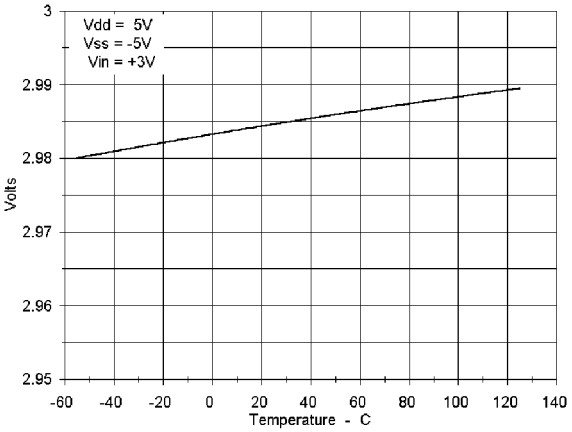
Graph 3. DAC Input Resistance vs. Digital Input Code



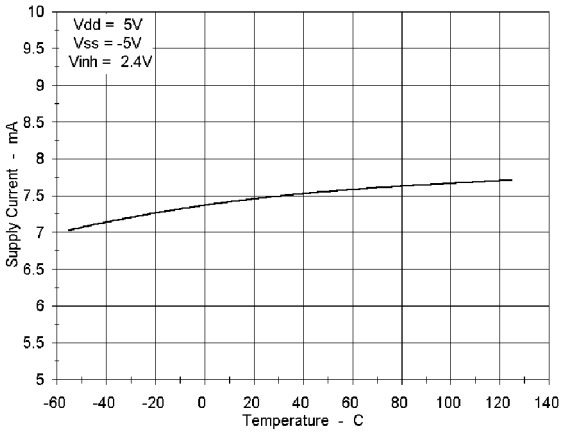
Graph 4. Linearity Error vs. Digital Input Code



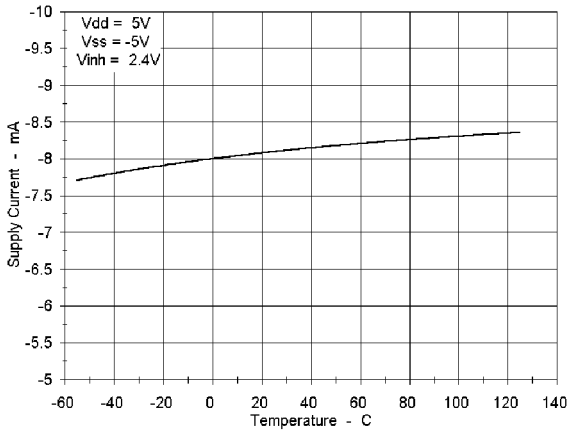
Graph 5. PSRR (DC) vs. Temperature



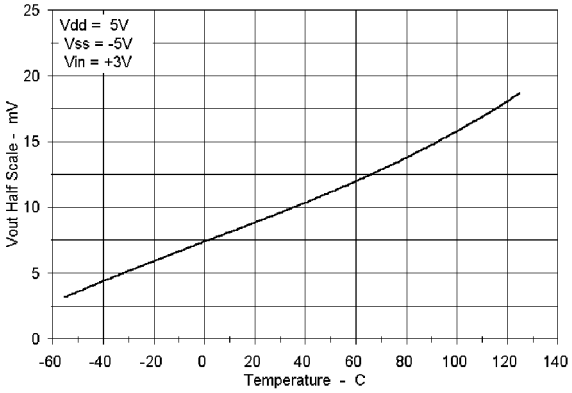
Graph 6. V_{OUT} Full Scale vs. Temperature



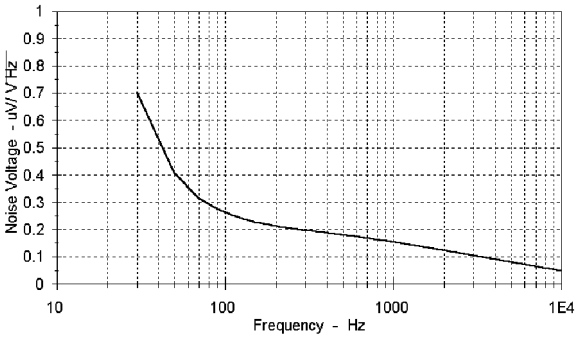
Graph 7. Supply Current (I_{DD}) vs. Temperature



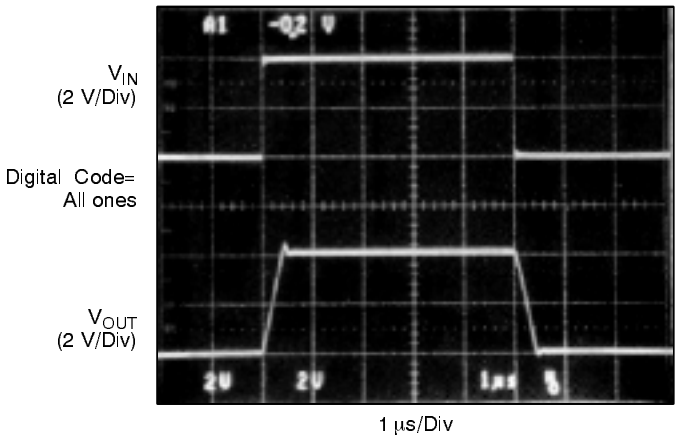
Graph 8. Supply Current (I_{SS}) vs. Temperature



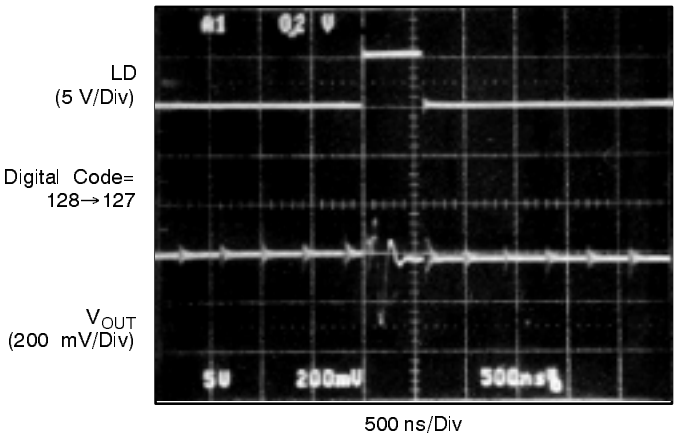
Graph 9. V_{OUT} Offset Error vs. Temperature



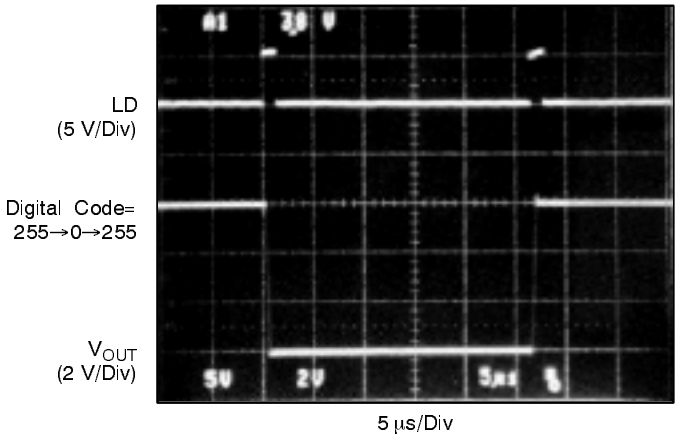
Graph 10. Voltage Noise Density vs. Frequency



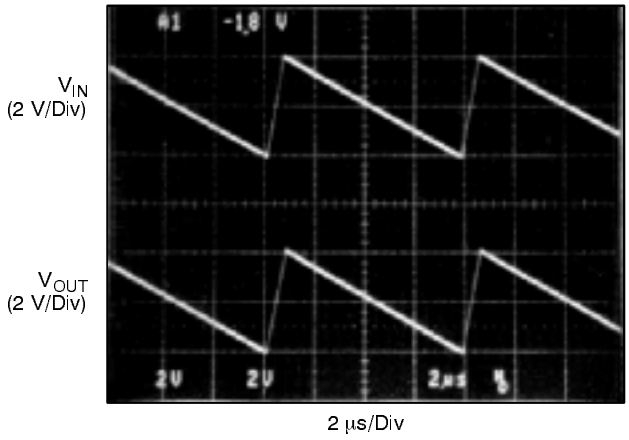
Graph 1. Pulse Response



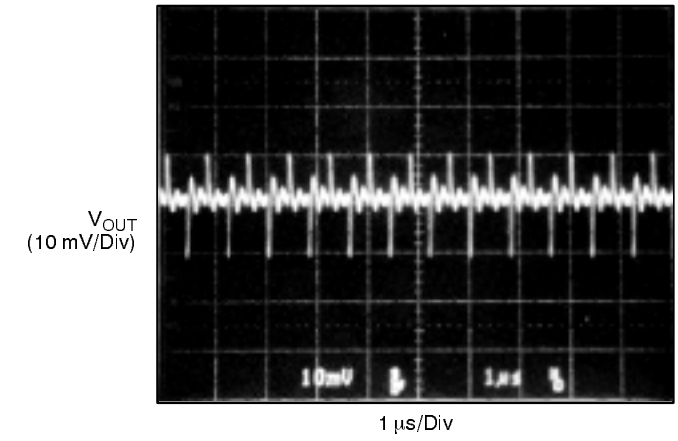
Graph 2. 1 LSB Digital Step Change



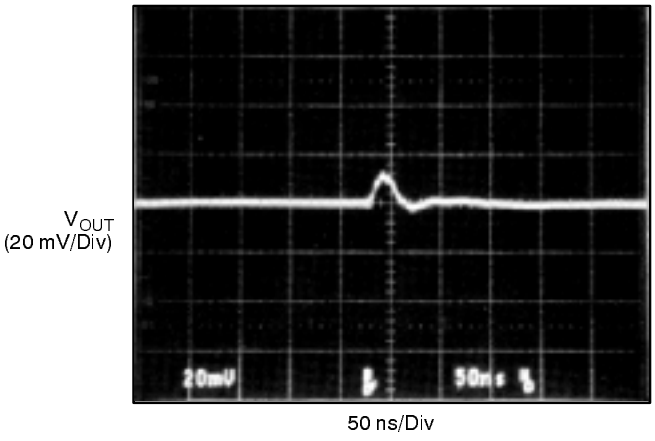
Graph 3. Settling Time



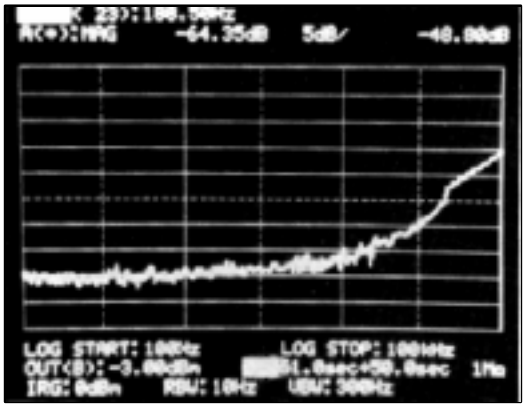
Graph 4. 128kHz Sawtooth Waveform Response



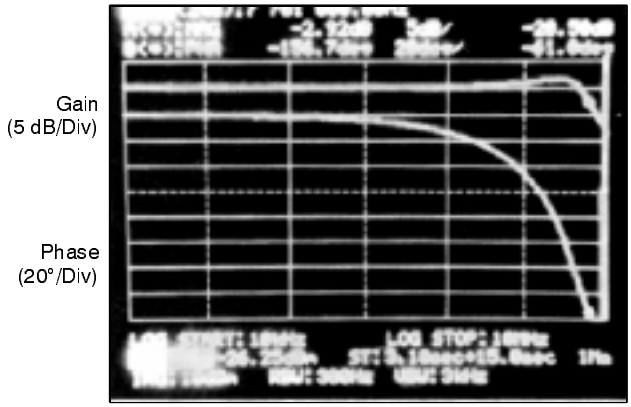
Graph 5. Clock Feedthrough



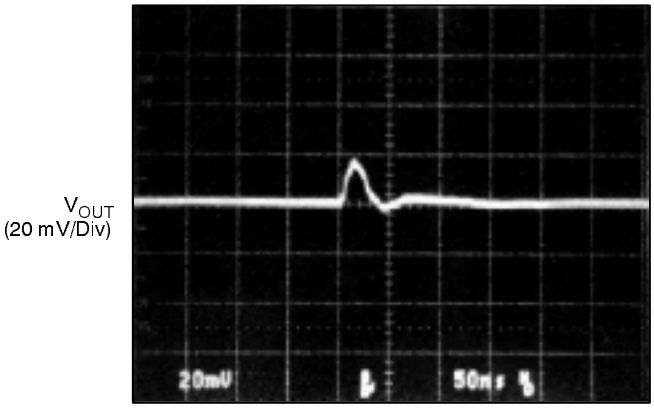
Graph 6. Digital Crosstalk



Graph 7. PSRR vs. Frequency



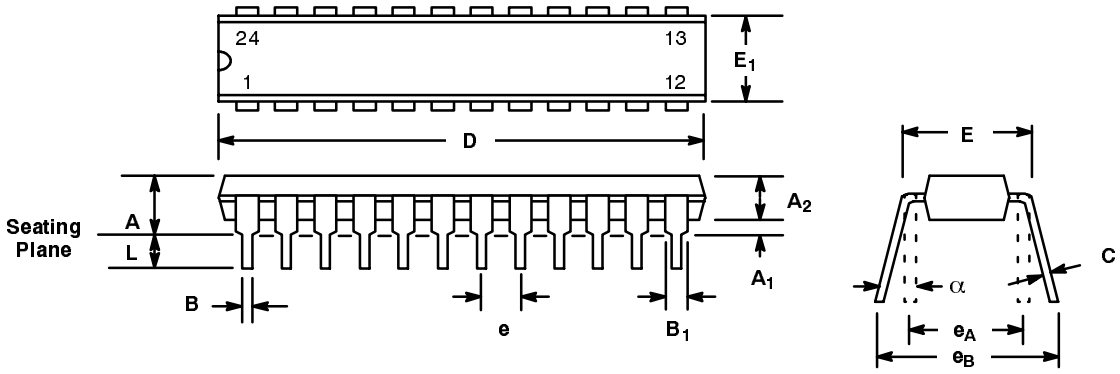
Graph 8. Gain and Phase vs. Frequency



Graph 9. Digital Feedthrough

24 LEAD PLASTIC DUAL-IN-LINE (300 MIL PDIP)

Rev. 1.00

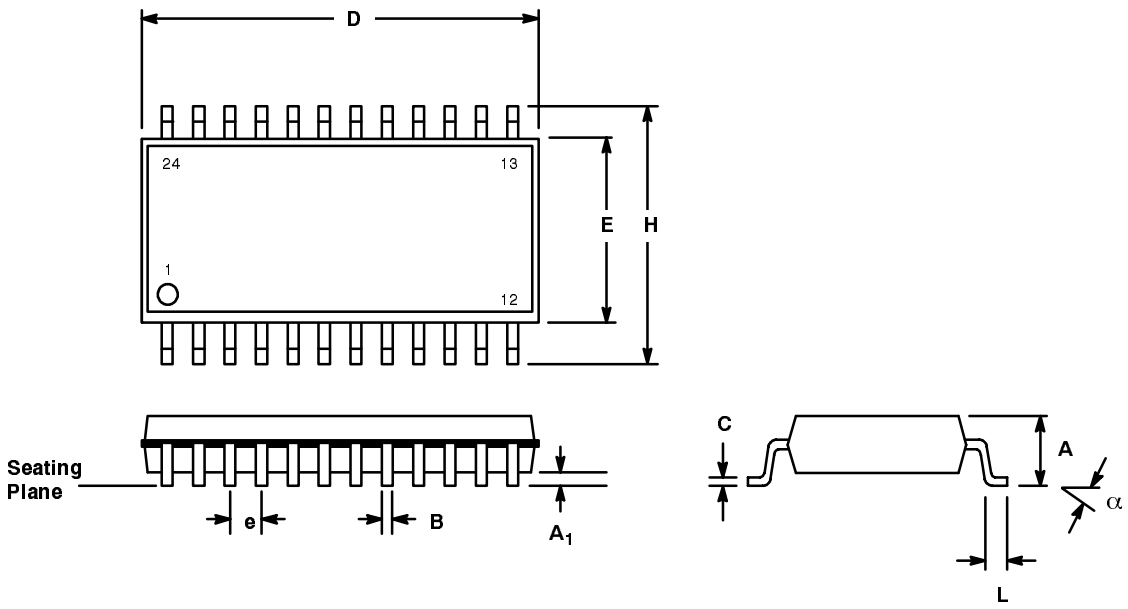


SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.145	0.210	3.68	5.33
A_1	0.015	0.070	0.38	1.78
A_2	0.115	0.195	2.92	4.95
B	0.014	0.024	0.36	0.56
B_1	0.030	0.070	0.76	1.78
C	0.008	0.014	0.20	0.38
D	1.125	1.275	28.58	32.39
E	0.300	0.325	7.62	8.26
E_1	0.240	0.280	6.10	7.11
e	0.100 BSC		2.54 BSC	
e_A	0.300 BSC		7.62 BSC	
e_B	0.310	0.430	7.87	10.92
L	0.115	0.160	2.92	5.08
α	0°	15°	0°	15°

Note: The control dimension is the inch column

24 LEAD SMALL OUTLINE
(300 MIL JEDEC SOIC)

Rev. 1.00



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.093	0.104	2.35	2.65
A1	0.004	0.012	0.10	0.30
B	0.013	0.020	0.33	0.51
C	0.009	0.013	0.23	0.32
D	0.598	0.614	15.20	15.60
E	0.291	0.299	7.40	7.60
e	0.050 BSC		1.27 BSC	
H	0.394	0.419	10.00	10.65
L	0.016	0.050	0.40	1.27
α	0°	8°	0°	8°

Note: The control dimension is the millimeter column

Notes

NOTICE

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